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CLIPPEDIMAGE= JP360161973A
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TITLE: PREPARATION OF NOVEL EPOXY RESIN
PUBN-DATE: August 23, 1985
INVENTOR-INFORMATION:

NAME

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APPL-NO: JP59014860

COUNTRY

N/A

APPL-DATE: January 30, 1984

INT-CL (IPC): C07D303/14; C08G059/20 ; C08G065/32 ;
C08G065/14

ABSTRACT:

NEW MATERIAL: An epoxy compound expressed by formula I
[R<SB>1</SB> is organic
compound residue having 1 active H atoms; n<SB>1</SB>,
n<SB>2</SB>...n<SB>l</SB> are integers 0~100, and the
sum thereof is
1~100; l is an integer 1~100; B is expressed by
formula II[X is
expressed by formula III, IV or V (R<SB>2</SB> is H, alkyl,
alkylcarbonyl or
arylcarbonyl)], and contains one or more groups expressed
by formula III in the
resin expressed by formula I].

EXAMPLE: The compound expressed by formula VI (n is 2 on
the average).

USE: An alicyclic epoxy resin compound, having rapidly
curable terminal epoxy
groups and improved heat resistance and electrical
characteristics without
containing chlorine, and applicable to preparation of
large-scale integrated
circuits (LSI) sealing materials, sealants for light
emitting diodes (LED) and
semiconductors and coating materials, etc.

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PREPARATION: An unsaturated compound expressed by formula VII (A is cyclohexane skeleton having vinyl group of formula VIII) is reacted with an epoxidizing agent, e.g. peracetic acid, if necessary in a solvent at -70°C to $+200^{\circ}\text{C}$ to give the aimed compound expressed by formula I .

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